

HVL145

Silicon Epitaxial Planar Pin Diode for Antenna Switching

REJ03G0434-0100

(Previous: ADE-208-1597)

Rev.1.00 Dec 07, 2004

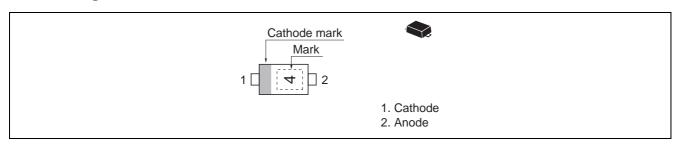
Features

- An optimal solution for antenna switching in mobile phones.
- Low capacitance. (C = 0.45 pF max)
- Low forward resistance. (rf = $1.8 \Omega \text{ max}$)
- Extremely small Flat Lead Package (EFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVL145	4	EFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	60	V
Forward current	I _F	50	mA
Power dissipation	Pd	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

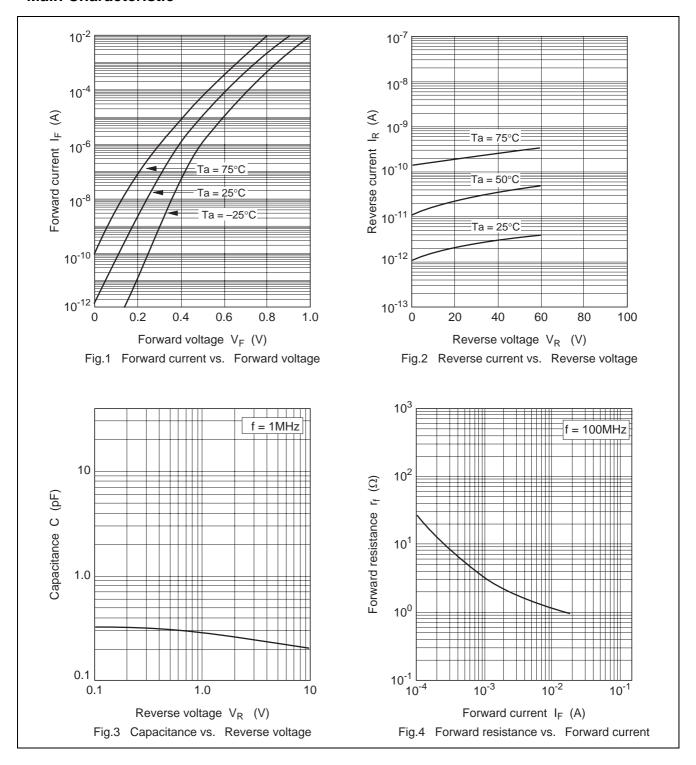
 $(Ta = 25^{\circ}C)$

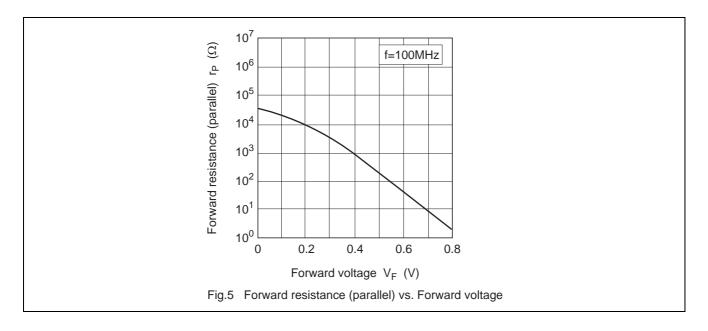
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R	_	_	100	nA	V _R = 60 V
Forward voltage	V _F	_	_	0.9	V	$I_F = 2 \text{ mA}$
Capacitance	С	_	_	0.45	pF	V _R = 1 V, f = 1 MHz
Forward resistance	r _f	_	_	1.8	Ω	I _F = 10 mA, f = 100 MHz
ESD-Capability *1	_	100	_	_	V	$C = 200 \text{ pF}, R = 0 \Omega$, Both forward
						and reverse direction 1 pulse.

Notes: 1. Failure criterion; $I_R > 100 \text{ nA}$ at $V_R = 60 \text{ V}$

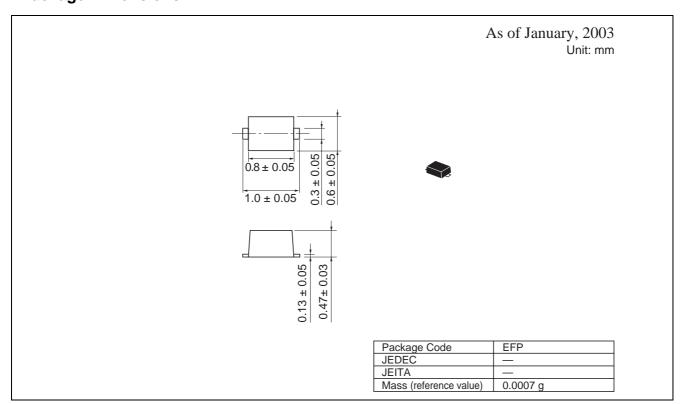
- 2. Please do not use the soldering iron due to avoid high stress to the EFP package.
- 3. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic





Package Dimensions



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Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001